



#### DISCRIPTION

## **FEATURES**

Multilayer ceramic structure Closed magnetic circuit Avoids crosstalk Excellent solderability High reliability

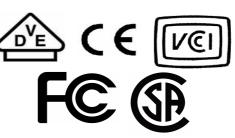
### **OPTIONS**

Tape & Reel is Standard (Qty: 2.000 Pcs) Bulk Packing Available for smaller quantites Tolerance: K=10%, M=20% is Standard, tighter Tolerance available (MOQ on request)

### **APPLICATIONS**

VCRs Mobile Radios Cordless Telephones Modems Global Position Systems Wirless Communications Equipment Network Systems Computer Products

# APPROVAL



### PHYSICAL CHARACTERISTICS

- Testing : (Equivalents acceptable) Inductance & Q-HP4195A + HP41951 DCR : VOAC-7412 ; SRF : HP8753C
- Solderability : 75% of the terminal Electrode shall be covered Preheat : 180°C ± 5°C for 2 ~ 3 minutes Solder temperature : 230°C for 4 seconds ± 1 second Flux : Emersion into methanol solution with Colophony for 3 to 5 seconds.
- IDC : The DC current at which tither the initial L value is decreased by 5% with the application of DC bias or the value of current at which the temparture of the element is increased by 20°C
- Operating Temperature : -40°C ~ 100°C

Properties	Test conditions		Value	Unit	Tol.
Inductance		L	8,2	μH	see Site 2
Q factor		Q	20		min.
DC-resistance		DCR typ.		Ω	typ.
DC-resistance		DCR max.	2,900	Ω	max.
Self-Res. Freq.		SRF	10	Mhz	min.
Test-Freq.			18	Mhz	
Rated Current		IDC	4	mA	max.
Saturation Current		Isat		mA	typ.

### **ELECTRICAL SPECIFICATIONS**

<ol> <li>This electronic component is meant to be used in general electronic equipment. Before the incorporation of this component into any equipment with higher and more reliable requirements such as aviation, aerospace, submarine, nuclear control, transportation, transportation signal, disaster prevention, medical, public information network, etc. or if there is a possibility of injuries or damages to the human body, Edcon</li> </ol>						SMT Multi-Layer Ceramic Chip Inductors	
	n network, etc. or must be informed	Part No.:	S11004-8R2				
performed on each electronic components used in electrical circuits that require high safety and reliability functions.					Customer:		
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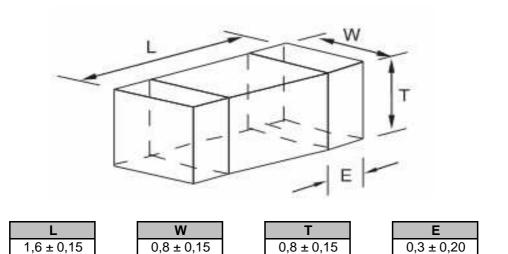
email: info@edcon-components.com





#### **TECHNICAL INFORMATIONS**

#### Dimensions (mm)



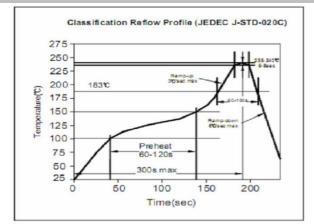
#### **Ordering Information**

Serie and Range

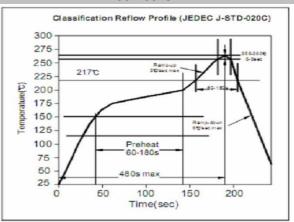
S11004-8R2

Tolerance	ROHS	Packing		
ĸ	R	TR		
, K	K			
<b>K</b> = 10%	<b>R =</b> ROHS	BU = Bulk Ware		
<b>M</b> = 20%	N = non ROHS	TR = Tape Reel		
<b>N</b> = 30%				

# Soldering Profile for Lead Free Soldering 235-240°C



# Soldering Profile for Lead Free Soldering 255-260°C



1. This electronic component is meant to be used in general electronic equipment. Before the incorporation of this component into any equipment with higher and more reliable requirements such as aviation, aerospace, submarine, nuclear control, transportation, transportation signal, disaster prevention, medical,						SMT Multi-Layer Ceramic Chip Inductors	
public information network, etc. or if there is a possibility of injuries or damages to the human body, Edcon -Components must be informed before the stage of design-in. Evaluation checks for safety have to be						Part No.:	S11004-8R2
performed on each electronic components used in electrical circuits that require high safety and reliability functions.					Customer:		
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